

In the Specification:

On page 1, after the title and before line 2 insert the following new paragraph:

This application is a continuation patent application of application Serial No. 10/043,885, filed January 9, 2002, (now pending), the entire contents of which are incorporated herein by reference.

Replace the paragraph beginning at page 9, line 4 of the Specification with the following paragraph:

Besides the already mentioned connecting points 1.1 to the rotor, the printed circuit board 1 includes a carrier substrate 1.2 and strip conductors 1.3 (see FIGS. 2 and 3). The material from which the carrier substrate 1.2 is made is a fiberglass-reinforced epoxy resin of the type FR4, and is therefore comparatively rigid. The strip conductors 1.3 are made of copper, which are applied to the carrier substrate 1.2 at a layer thickness of approximately 35 μm . The strip conductor ends 1.5 located opposite the connecting points 1.1 are soldered to a so-called FFC plug 100 (FFC means flexible flat cable) schematically represented by the box 100 of FIG. 1. The appropriate flat cable then constitutes a connection between the printed circuit board 1 and the camera 4. The other strip conductor ends 1.6 are electrically connected with the tilt drive 5.